Solder paste WINDOT B-005-NP303 T6

Product description

GENMA jetting solder paste – our jet dispenser solder paste WINDOT shows an excellent performance. Uniform dots as small as 200µm can be jetted in a continuous process at high speed. The result are attractive soldering joints that are surrounded by clear flux residues. The solder paste requires to be soldered under nitrogen reflow. Cleaning after soldering is not necessary.

Technical properties

	Specific value	Testing method
Alloy	Sn 96,5 / Ag 3,0 / Cu 0,5 / SAC305	
Melting temperature range	217 - 221	IEC61189-11

Compliance

Dated 13.11.2025

Conform with RoHS-Regulation 2011/65/EU and 2015/863/EU.

Contains no substances (SVHC-list) more than threshold (0,1%) according to REACH legislation EG Nr. 1907/2006.

Contains no substances as defined by the Toxic Substance Control Act (TSCA) of the United States Environmental Protection Agency.

Contains no substances according to POP Regulation EU 2019/1021.

Contains no Per- and PolyFuluoroAlkyl Substances (PFAS).

Contains no phthalates or latex.

Contains no substances according to California Proposition 65.

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